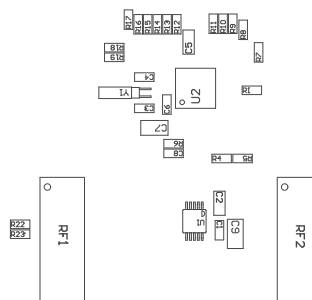


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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-CAPTIVATE-REMOTECONTROL SUN REV: Not In VersionControl
	TID #: TIDM-CAPTIVATE-REMOTECONTROL
PLOT NAME = Top Assembly Drawing	GENERATED : 9/14/2016 2:20:38 PM TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDM-CAPTIVATE-REMOTECONTROL SUN REV: Not In VersionControl	
	TID #: TIDM-CAPTIVATE-REMOTECONTROL	
PLOT NAME = Bottom Layer Assembly Drawing	GENERATED : 9/14/2016 2:20:38 PM	TEXAS INSTRUMENTS

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